

25 Watts • 50 Volts • Pulsed & CW 50MHz-1GHz Broadband GaN Amplifier Ceramic SMT Package

#### **GENERAL DESCRIPTION**

The 0510GN-25-CP is a COMMON SOURCE, class-AB, GaN on SiC HEMT transistor amplifier for 50MHz-1GHz broadband pulsed and CW RF power applications. The transistor is housed in a Ceramic SMT package with high-thermal conductivity to provide superior electrical and thermal performance with excellent reliability & ruggedness.

#### **FEATURES:**

- Wide-band 50MHz-1GHz general purpose driver applications
- Single lumped-element Broadband application circuit
- Ideal for Pulsed Radar, Avionics, ISM, and CW Communication
- Commercial & Military Applications
- 25 W Pulsed/CW Psat, 16 dB Power Gain and 50 % Drain Efficiency
- Low-cost Ceramic SMT package with excellent RF & Thermal performance, reliability & ruggedness
- 50V Bias Operation with high breakdown voltage

### **ABSOLUTE MAXIMUM RATINGS**

**Maximum CW Power Dissipation** 

Device Dissipation @ 25°C 25 W

**Maximum Voltage and Current** 

Drain-Source Voltage (V<sub>DSS</sub>) 125 V Gate-Source Voltage (V<sub>GS</sub>) -8 to +0 V Supply Current (I<sub>DD</sub>) 1400 mA

**Maximum Temperatures** 

Storage Temperature ( $T_{STG}$ ) -55 to +150° C Operating Junction Temperature +200 °C

# PACKAGE OUTLINE Ceramic SMT 160X200 MIL



### TYPICAL CW BROADBAND PERFORMANCE SUMMARY 1 @ 25°C

Parameter	Units	50 MHz	300 MHz	500 MHz	700 MHz	900 MHz	1 GHz
Output Power Psat	W	33	36	31	27	29	27
Power Gain	dB	16	16.5	16	15.5	15.7	15.5
η⊳ Drain Efficiency	%	85	75	61	50	52	52

<sup>&</sup>lt;sup>1</sup> Bias Condition: Vdd=+50V, Idq= 120 mA (Vgs= -2.0 ~ -4.5V typical), Pin = 29 dBm RF performance measured on the recommended broadband evaluation circuit board.



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### DC FUNCTIONAL CHARACTERISTICS @ 25°C

Symbol	Characteristics	Test Conditions	Min	Тур	Max	Units
I <sub>D(Off)</sub>	Drain leakage current	$V_{GS} = -8V$ , $V_{DD} = 50V$			2	mA
I <sub>G(Off)</sub>	Gate leakage current	$V_{GS} = -8V$ , $V_{DD} = 0V$			0.4	mA
BV <sub>DSS</sub>	Drain-Source breakdown voltage	V <sub>GS</sub> =-8V, I <sub>DD</sub> = 4 mA	125			V
V <sub>GS(TH)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =50V, I <sub>DD</sub> = 4 mA	-4.8	-3.4	-2.5	V

### **ELECTRICAL CHARACTERISTICS<sup>1</sup> @ 25°C**

Symbol	Characteristics	Test Conditions <sup>1</sup>		Тур	Max	Units
Pout	Output Power	Pin=0.8W Freq= 50 MHz -1000 MHz, CW		28		W
Gp	Power Gain	Pin=0.8W Freq= 500 MHz, CW		16		dB
η <sub>D</sub>	Drain Efficiency	Pin=0.8W Freq= 500 MHz, CW		61		%
Pout	Output Power	Pin=0.8W Freq= 1000 MHz, Pulsed <sup>2</sup>		31		W
Gp	Power Gain	Pin=0.8W Freq= 1000 MHz, Pulsed <sup>2</sup>		16		dB
η <sub>D</sub>	Drain Efficiency	Pin=0.8W Freq= 1000 MHz, Pulsed <sup>2</sup>		54		%
Dr	Droop	Pin=0.8W Freq= 1000 MHz, Pulsed <sup>2</sup>		0.1		dB
VSWR-T	Load Mismatch Tolerance	Pin=0.8W Freq=1000 MHz			5:1	
Өјс	Thermal Resistance including PCB, Tbase = 85 °C	Pulse Width=1 mS Duty=10%		1.7		°C/W
		CW		4.2		

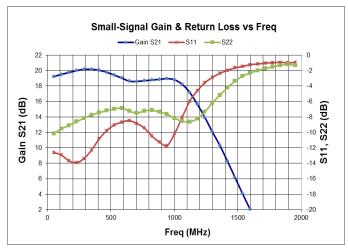
<sup>&</sup>lt;sup>1</sup> Bias Condition: Vdd=+50V, ldq= 120 mA (Vgs= -2.0 ~ -4.5V typical), CW

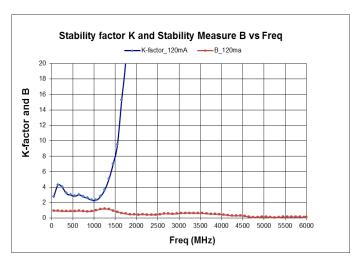
 $<sup>^2</sup>$  Bias Condition: Vdd=+50V, Idq= 80 mA (Vgs= -2.0 ~ -4.5V typical), PW = 1mS, DC = 10% RF performance measured on the recommended broadband evaluation board.

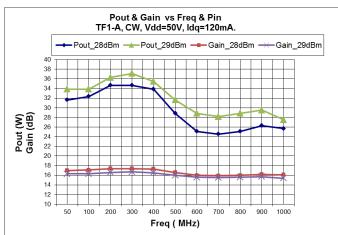


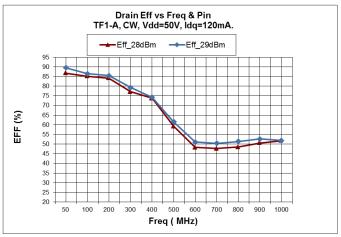
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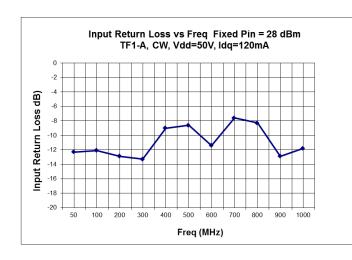
### CW PERFORMANCE PLOTS @ VDD=50 V, IDQ = 120mA, T = 25°C

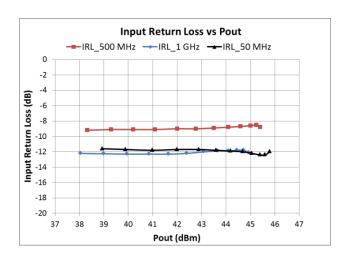






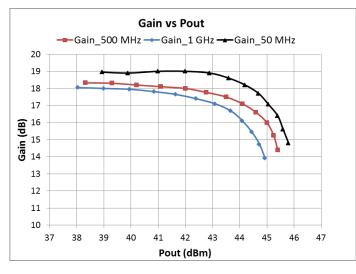


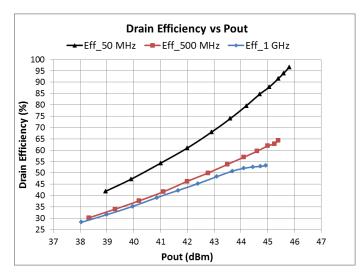


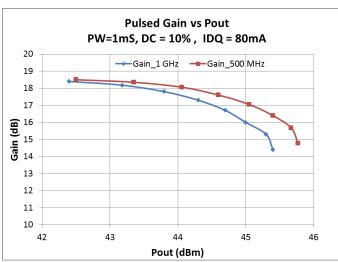


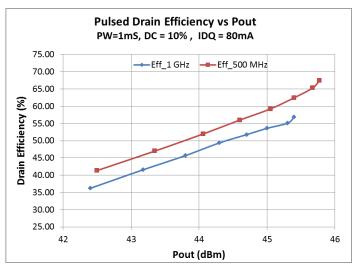


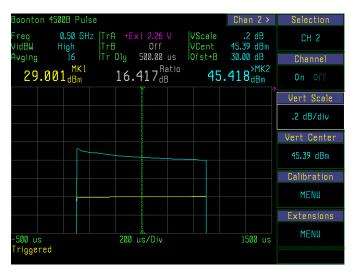
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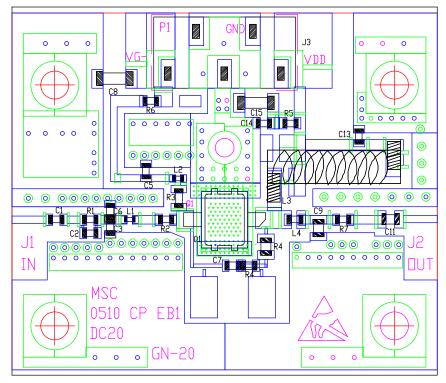






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# EVALUATION BOARD LAYOUT 0510 CP EB1 ASSEMBLY DIAGRAM AND BOM FOR BROADBAND 50 MHz to 1 GHz



Board Material: Rogers RO4003C, 12 Mil Thickness, Er = 3.38, 1 OZ Cu 8 Mil Dia Vias below package, Qty: 85, Solid Plated Cu Filled. Board Size: 1.5 x 1.3 inches

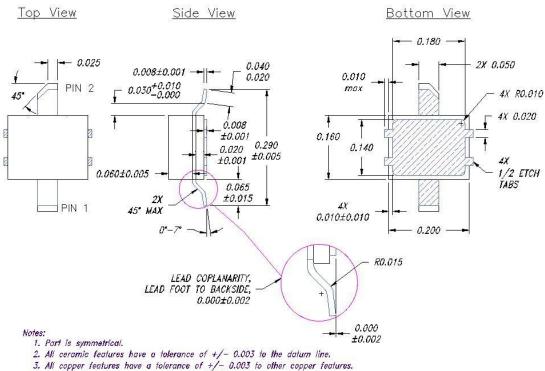
Item	Description 50 MHz - 1 GHz		
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C2	0603, 12 pF, ±5%, 250V, ATC 600S		
C3	0603, 3.3 pF, ±5%, 250V, ATC 600S		
C6	0603, 1 pF, ±5%, 250V, ATC 600S		
C9	0603, 1.8 pF, ±0.25pF, 250V, ATC 600S		
C13	0603, 470 pF, ±5%, 100V, AVX, X7R		
C1, C11, C7	0603, 1000 pF ±10%, 100V, AVX, X7R		
C5,C14	0603, 10000 pF, ±10%, 100V, AVX, X7R		
C8,C15	1206, 4.7 uF, ±10%, 100V, AVX, X7S		
R1	0603 6.2 Ω		
R5,R6,R7	0603 0.0 Ω JUMPER		
R2	0603 3 Ω		
R3	0603 24 Ω		
R4	NDP-0505WA 1K ohm, 5%, IMS		
L1	0402HP, 2.7 nH, 5% Coilcraft		
L2	0402PA, 5.8 nH, 5% Coilcraft		
L3	4310LC-132KEB, 1.3uH, Coilcraft		
L4	0603HP, 6.0 nH, 5% Coilcraft		
J3	TSM-105-01-S-SV-A, SAMTEC		
Q1	0510GN-25-CP		
Note:			
Board Material: Rogers RO4003C, 12 Mil Thickness, Er = 3.38, 1 OZ Cu			



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#### **CERAMIC SMT PACKAGE 160X200 MIL OUTLINE & DIMENSIONS**

#### All Dimensions are in inches



- 4. All ceramic features have a tolerance of +/- 0.005 to copper features. (i.e. leadframe alignment to ceramic is +/- 0.005.)

PIN	FUNCTION
1	Gate (RF/DC Input )
2	Drain (RF Output/DC Input)
Backside Exposed Pad	Source (RF/ DC GND & Thermal Pad)

#### Notes:

1. Backside exposed pad must be connected to Solid Plated Cu filled vias for optimum RF & Thermal performance. See recommended evaluation board layout



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#### **Revision History**

Revision	Date	Affected Section(s)	Description
1.0	5-13-15	-	Initial Preliminary Release
2.0	6-21-15	Page 1	Package photo updated